Reliability Society

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Editor:

Bruce Bream

President's Report

he July Reliability Society Administrative Council (AdCom) meeting was held at IEEE Headquarters in Piscataway, New Jersey. A few of the highlights of the meeting on Friday were a lecture and tour of the headquarters facility conducted by Dr. Irv Engelson. We had the opportunity to meet three IEEE presidents during the tour - Dr. Martha Sloan, Dr. Troy Nagle, and Dr. Thomas Cain. On Saturday, Dr. Troy Nagle, President of IEEE



and Dr. Bruce Eisenstein, Director of Division IV attended our meeting and made presentations to the AdCom. The Reliability Society signed a contract with the IEEE Educational Activities Department (EAD), to sponsor a videoconference in 1995. The Reliability Society will advance \$30,000 to cover costs

such as studio production and marketing. The initial \$30,000 in revenue will be returned to the Reliability Society and additional revenue will be split 50/50 with IEEE EAB.

The IEEE Technical Activities Board (TAB) has a TAB Society Review Committee which reviews all societies every 5 years (approximately 37 reviews in each 5-year period). The Reliability Society is scheduled for review this year. The initial material for this presentation was reviewed at our July meeting. I expect to have the TAB societies critique of our Society to present to you in the next newsletter.

Our next AdCom meeting is scheduled for the University of Maryland on October 1, 1994. A video tape of the 1996 IEEE Presidential Candidates Debate which was held in Denver, Colorado during June 1994 will be shown to assist AdCom members and other attendees in casting informed votes.

I know you have all received your ballots for the Reliability Society Administrative Committee candidates. I hope you have all taken the time to vote for your leadership.

> W. Thomas Weir President, IEEE Reliability Society

Editor's Column

I regularly get notices of conferences that unfortunately are not timely to our members. Many of them may miss appearing in our call for papers section. This is due to our quarterly publication schedule as well as late notice from the conferences. If you have a conference, please let me know about it early. I can easily publish a short notice with the dates, location and phone number for more information if the full conference notice is not prepared. Remember to notify the newsletter editor, I'm here to help but I need timely information.

The information superhighway is here and ready for use. I encourage all of you to take advantage of it by at least finding out your Internet Email address, if you have one, and let others know. I would like to be able to show an email address for anyone who's name appears in the newsletter. Any comments or input to the newsletter can be sent to my Email address shown on this page. Email facilitates the flow of information and It also makes it a lot easier for me to put the newsletter together (my fingers only go so fast). You should also be able to take advantage of the many services offered by IEEE over the Internet.

Bruce Bream Editor, Reliability Society Newsletter

Reliability Society Newsletter Inputs

All RS newsletter inputs should be sent to:
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The schedule	he schedule for submittals is:		
Newsletter	Due Date		
January	November 19		
April	February 26		
July	May 28		
October	August 27		

ADVERTISING RATES

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All copy that contains graphics or special fonts must be camera-ready or delivered on computer disk and be received by the due dates indicated.

Ad Size	One Time	2-3	4+
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Third Page (vertical)	\$240	225	210
Quarter Page	\$205	190	180
Eighth Page	\$120	110	100

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Chapter Activities

Boston Chapter

Greetings from the Boston Chapter! We are coming off of a very successful season. Among the highlights was the 32nd annual Spring Symposium, which featured Mr. Kenneth Olsen, former CEO of Digital Equipment Corporation, as the keynote speaker. The theme for the symposium was "Reliability - It's Not Just Hardware Anymore".

Our elected officers for 1994-1995 season are as follows: Chair: Brian McOuillan

Vice Chair: Keith Burger Treasurer: Donald Markuson Secretary: Philip Tsung

Additional AdCom positions are as follows:

Monthly Programs: Harvey Bloom Publicity: Ruth Evans Arrangements: Giora Kedem-Kuller Steering Committee Chair:

Anita Cederholm Lecture Series Chair: Keith Burger Symposium Chair: Jim Fahy Symposium Program: Warren Snow Technology Development Chair:

Gene Bridgers

We are proud to observe that product reliability has steadily improved over recent years. However, we recognize that our profession is changing. There continues to be a shift in emphasis regarding the traditional reliability tasks, especially in the DOD arena. These changes have directly affected much of our membership. Many companies have replaced traditional methods with new approaches to achieve their reliability goals. Therefore, the focus for this year's AdCom is *change*. Appropriately, Mr. Harvey Bloom will kick off this season's monthly meeting line-up by presenting "Reliability in the '90s - Doing More With Less" on September 21st.

Our Fall Lecture Series, "Reliability Analysis and Testing", will present a primer on R&M objectives, methods, and implementation, using the Rome Laboratory Reliability Engineer's Toolkit as a guide. It is intended to educate as well as identify topics of interest for future events.

Looking into 1995, next April's Spring Symposium theme is "Application of Reliability Tools".

All in all, we are looking forward to another good year!

Brian McQuillan Boston Chapter Chair

Los Angeles Chapter

On June 30th, Larry Stern, IEEE Congressional Fellow, briefed us on his experience on Capitol Hill. He presented his forecast of where Aerospace will be in the next 5 years.

On July 28th, we heard Charles Finnila discuss combining data compression and encryption to increase data storage, speed data transmission, and provide data security. Charles, retired from Hughes Aircraft, will be presenting this topic at Wescon in September.

Meetings in planning: September 7th - We are having a joint meeting with the Los Angeles Chapter of ACM on Visual Programming for test and measurement by Edmund C. Baroth, of Jet Propulsion Laboratory. Later in September, Marco Garcia, of Hughes Aircraft, is speaking on

"Commercial Components in Military - Are We Ready?" In October, another joint ACM meeting will be held on Artificial Intelligence by Mr. Peter Coffee. Later in October, Dan Erwin of the University of Southern California will present Neural Network Tools and Applications.

Winnfort Myles, Chapter Vice Chair and also current LA Council PACE Chair, is organizing an Exhibit and Presentations at the Del Amo Mall during the 1995 National Engineers week. He, along with other LAC and Reliability Society Chapter members, are working to obtain presentations and exhibits from local companies.

Our Bulletin Board is very active with over 400 subscribed members. Membership is free. We offer meeting information, Jobline, E-Mail, Video Tape Exchange information, Shareware and Demos. The BBS number is (818)768-7644, 300-2400 baud.

Our Videotape Exchange program currently has over 150 videotapes available. The latest information can be read and downloaded through the BBS.

Loretta Arellano Los Angeles Chapter

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continued on next page

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(continued from page 3)

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Please help us keep our list of chapter chairpersons current. Send your changes/updates to the Newsletter Editor or the Society Secretary (see page 2 for addresses).

IEEE Email Forwarding Service

IEEE members and volunteers can request a personal e-mail name (alias) from the IEEE. An alias of the form "i.name@ieee.org", where "i" is the first initial, and "name" is the last name will be designated to each member. Messages addressed to "i.name@ieee.org" will automatically be forwarded to the actual Internet address, whether it be at the IEEE Service Center of around the other side of the world. This forwarding service is provided for IEEE members and staff in order to simplify the myriad of computer mailbox addresses. The intent is to assist members to use their most convenient local electronic mail capability and, as simply as possible, exchange messages with any other member of staff person, or request services electronically. These aliases are usually much easier to remember and simpler to use than the real address.

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- Your IEEE member number (if your are a non-member volunteer, e.g. working on a Standards group please ask your group chair who will be an IEEE member to process your request)
- Your current major IEEE volunteer activity involvement, if applicable

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IEEE (Leesburg) CAE Workshop at RAMS

The IEEE (Leesburg) Computer Aided Engineering (CAE) Workshop on Concurrent Engineering (CE) for Integrated Product Development (IPD) joined forces with RAMS at the 1994 RAMS Symposium. The Workshop will be held in conjunction with RAMS again, in January 1995, with the Workshop starting on Monday morning. Now you can attend both for the price of one. If you are responsible for implementing design automation within your company, or are a CAE Developer/Supplier of IPD or R&M tools, or are an IPD Team member (such as Reliability or Maintainability Engineering), then this Workshop is for you! Attend, learn, make contacts, participate, and help influence the CAE direction in its support of IPD Teams within our Industries.

Register for RAMS and attend the 1995 Symposium in Washington, D.C. If you have Workshop questions or want more information, please contact Dennis Hoffman (214)480-1000 or Don Nilson (817)763-3439. Se you at the Workshop at RAMS.

National Engineers Week 1995 Will Highlight Engineering in Everyday Life

The National Engineers Week Committee has announced that next year's celebration will emphasize the engineering of everyday life. The 45th annual National Engineers Week, scheduled for February 19-25, 1995, will feature a variety of national and local programs designed to increase public appreciation of the engineering profession by highlighting engineers' contributions to American life. Through its United States Activities division. The Institute of Electrical and Electronics Engineers Inc. joins 16 other engineering societies and several major corporations as sponsors.

National Engineers Week 1995 is chaired by the American Institute of Chemical Engineers (AIChE). Leslie G. McCraw, chairman and CEO of Fluor Daniel Inc., will serve as honorary chairman. The theme for the week is "Engineers: Turning Ideas into Reality," while the Discover "E" classroom program will

inspire students to "Discover Engineering Every Day."

Discover "E" involves many thousands of engineer volunteers who motivate students to pursue math and science studies. Other national programs for the week include: technology fairs in shopping malls, science centers and local libraries; and the third annual Future City Competition, with engineers helping teams of middle-school students design cities of the 21st century.

Planning kits for National Engineers Week 1995 contain everything needed for individuals, Sections or companies to participate in the week's activities, and will be available in October. For free kits, contact National Engineers Week, P.O. Box 1270, Evans City, PA 16033, Tel: (412)772-0950. For more information on National Engineers Week, call National Engineers Week Headquarters at (703)684-2852, or IEEE Public Relations in Washington at (202)785-0017.

FREE PROCEEDINGS

The Reliability Society has surplus copies of the 1992 and 1994 IRPS Proceedings and of the 1993 and 1994 RAMS Proceedings. Free copies will be sent on request, so long as supplies last, to:

- Reliability Society members
- Instructors in reliability (The society will be happy to supply a copy for every member of a class on reliability.)
- Technical Libraries
- Those interested should indicate how many copies are desired and which proceedings are wanted. We have only those listed above. Send requests to Anthony Coppola, IITRI, 201 Mill St., Rome NY 13340. Tel: (315) 339-7075 (prefer fax or e-mail). Fax: (315) 337-9932. E-mail: acoppola@mail.iitri.com

Electronic Bulletin Boards

Los Angeles IEEE Chapter

(818) 768-7644 300-2400 Baud (8N1) Free Membership — (400+ members) Meeting information, Jobline, Email, Video Tape Exchange Information. Shareware an Demos

Statistics Bulletin Board System

(316) 265-3036 1200-2400 Baud (8N1) Free Membership Statistics, Reliability

Computer Aided Logistics System (CALS)

(703) 321-8020 300-9600 baud 8N1 The CALS BBS is reached through this number to the National Technical Information Service (NTIS) BBS. Membership is free.

JPL/NASA Radiation Effects **Data Bank**

Test data on Single Event Effects and total-dose for electronic parts BBS: (818) 393-4156, 1200 baud, 8N1 (818) 306-6920, 1200 baud, 8N1 FTP: radata.jpl.nasa.gov (137.79.11.2), Enter userid 'radata' & password 'auest'

Sysop: Keyvan Eslami, (818)354-1715, email: keyvan_eslami@jpl.nasa.gov After logon hit return and type RADATA in response username, no password required.

DOD Field Failure Return Program (FFRP) Reliability Bulletin Board

This Bulletin Board provides information concerning the DOD FFRP program as well as providing a vehicle for both commercial and government users to exchange ideas and information on component and system problems.

1200 baud or less 8 Data bits, no parity, 1 stop bit (315) 339-7120, Access (315) 339-7043. Questions

October 1994 **Reliability Society Newsletter**

ADCOM Meeting Summary

16 July 94 AdCom Meeting – Piscataway, NJ

Dick Kowalski presented the budget and informed us that our net worth had increased 50% (\$155.8k). He projects another \$50k surplus this year.

Meeting News:

The next AdCom meeting is scheduled for October 1st at the University of Maryland. Dick Doyle will hold his tech ops meeting on September 30 (Friday preceeding the AdCom meeting). RAMS attendance was down resulting in a potential loss. This loss is shared by the 9 sponsors, therefore we may lose our seed money. IRPS had 1000 in attendance, the best ever. This was due to the lcoation being in the Silicon Valley location. Thre was a discussion of whether we prefer AdCom meetings on Saturdays. The survey that Henry Hartt sent out shows that it doesn't make a difference. Those who pay their own way get better rates if they travel on weekends (but Monday meetings are just as good).

Transaction News:

Hank Malec presented the status of the committee formed at the January AdCom

IEEE-USA Government Relations

IEEE-USA government relations information is available by

electronic mail through the Internet. Information currently

available includes a copy of IEEE-USA's Federal Legislative

IEEE-USA position statements (info.ieeeuse.pos@ieee.org),

(info.ieeeusa.policy@iee.org), the IEEE-USA Legislative Re-

ments, send an email request via Internet to the indicated

port newsletter (info.ieeeusa.legrpt@ieee.org), and informa-

a chronological log of IEEE-USA testimonies, comments,

and communications with public policy-makers

tion on the IEEE-USA pensions reform efforts

Agenda (info.ieeeusa.agenda@ieee.org), a list of current

Information on the Internet

to review the criteria for the Transactions. This committee is trying to make editing more efficient. Hank also presented a Transaction composite for Baselining. He suggested benchmarking it to SAE Communications in RMS Journal. Hank to report at the January AdCom meeting. He recommended having a separate morning meeting on this issue in January.

Tom read a letter from the U.S. Army praising the editor of the Transactions.

A motion was presented whereby at the end of 1994, at the expiration of the existing contract, we should replace the existing paid managing editor with 3 volunteers. Discussions followed including cost comparisons. The issue was raised regarding whether we could do the Managing Editor's job ourselves. A vote was taken and the motion lost.

Tech Ops News:

Loretta Arellano, for Irv Doshay, announced the course on Software Reliability that is being offered by California State University at Dominguez Hills is being taught by Myron Lipow.

Mr. Roger Lockwood has been working on a Software Safety Systems Document originally for the U.S. Air Force, but

now to be channeled through an industry handbook. He is seeking support of the Society to develop this handbook under the auspices of IEEE. Loretta will ask Roger for a formal plan by the next Ad-Com meeting at which we can decide on a position.

Dennis Hoffman reported that the CAE Workshop has been integrated into RAMS. He also reported on Project Aires.

Mike Cushing reported on the results of the questionnaire appearing in the April Newsletter. A summary of the results will be submitted to the Newsletter.

Other News:

Marvin Roush reported that there has been a decrease in periodical subscriptions and membership. Total membership is down 6% from last year.

Hank Malex presented charts showing the number of people who only belong to the Reliability Society (R-07) and those who belong to 2 or 3 other societies. This could be used as a marketing tool to get those of the other societies to join the Reliability Society.

Joe Gruessing reported that he received one call from a member who received the wrong proceedings. Last year many calls were received from members who were mailed the RAMS proceedings instead of the IRPS and vice-a-versa. Joe reported that he has been receiving great support from Headquarters in sending material to members.

Bruce Bream is looking for support on the Newsletter. Bruce has asked Tom to appoint an associate editor.

Dick Doyle reported that Dev Reheja will be giving a presentation on Maintainability at the October AdCom meeting.

Sam Keene reported that we are on schedule for the video conference. Presenters are Ted Keller, John Musa, and Sam Keene. The motion to authorize \$30,000 for the course was approved.

Tom Weir reported that each Society periodically gives reports of their activities to the IEEE Technical Activities Board (TAB). It is our turn and in August he must provide input to TAB.

Loretta Arellano Secretary, Reliability Society

Reliability ADCOM Meeting Schedule

IEEE RELIABILITY SOCIETY ADCOM MEETING University of Maryland September 30 - October 1, 1994

Friday, September 30, 1994

The Inn and	Conference Center (1-800-727-8622) lvd. at Adelphi Road, College Park Technical Operations Committee	R. Doyle		
6:30-????	Dinner at the Chef's Secret	andment #		
Saturday, October 1, 1994				
8:00-8:10	Engineering Classroom Bldg, Room (Call to Order	T.Weir		
8:10-9:30	Vice Presidents' Reports	1.VVeil		
8.10-9.30	Meetings	H. Hartt		
	Membership	M. Roush		
	Publications	J. Gruessing		
	Technical Operations	R. Doyle		
	Junior Past President's Report	S. Keene		
	Video Conference Program Discussion			
9:30-11:00		llano,B. Bang,		
0.00 11.00		J. Gruessing,		
		artt, S. Keene,		
		ski, M. Roush		
11:00-11:30	R&M Council	A. Plait		
11:30-12:00	Reliability Society Audit Debrief	T. Weir		
12:00-1:00	Lunch			
1:15-1:30	Funding for Eastern European	J. Gruessing		
	Libraries			
1:30-2:00	Maintainability Discussion	D. Raheja		
2:00-2:15	IRPS & RAMS Proceedings Orders	A. Coppola		
2:15-2:30	Constitution Revision (Introduction)	T. Weir		
2:30-3:00	Reliability Society BOD Proposal	B. Bang		
3:00-3:30	& Chapters for China and India Old & New Business	T. Weir		
3:30 —	IEEE Presidential Candidate Debate	T. Weir		
3.30 —	Video or Adjourn	i. vveii		
	video of Adjodiff			

Future meetings will be announced in the newsletter. The first two ADCOM meetings held each year are held concurrently with the RAMS and IRPS conferences. The IRPS is scheduled for Las Vegas in 1995. A conference may be more justifiable for you to attend, so please start your paperwork associated with a conference and plan on attending an ADCOM meeting in the same trip. Unfortunately the Reliability Society is unable to provide any monetary support to our meetings, but you can count on us buying you a "Free Lunch or Dinner". You might even want to volunteer for some future activity or join a committee.

Technology Policy Council Representatives

I am pleased to announce that the IEEE RELIABILITY SOCIETY has nominated for the second year 7 members to the IEEE United States Activitiy Board (USAB), Technology Policy Council. The representatives are shown along with their telephone numbers and field that they support. Most of these representatives have been active council members for one or more years.

Any Reliability Society member wishing to find out more about any of these USAB activities or desiring to attend a meeting is cordially invited as a guest. However, please notify either myself or one of the Technology Policy Council representatives if you plan to attend.

As you might know, our members are very active with the Technology Policy Council Committees in addition to their support of the Technical Operations Activities or other Reliability Society Activities. They are all extremely knowledgeable as well as energetic.

We try to keep active with other groups and to share the knowledge that is available. In an attempt to build on this sharing, we invite you to contact these representatives and ask for information to be mailed to you. This information typically would be recent meeting minutes and special white papers. If you would like to be considered for one of these mailing lists, please let me know so that I can coordinate it. In the future we intend to have a column for articles about each of the Technical Operations Activities.

If you have any questions or need further information, please do not hesitate to call me, or write to my address listed below.

Richard L. Doyle Registered C.E.& E.E.(CA) REE No. 8795, RCE 22955

IEEE RELIABILITY SOCIETY NOMINEES FOR TECH. POLICY COUNCIL - AUGUST 1994

COMMUNICATIONS AND INFORMATION POLICY: Mr. Hank Wolf, 2111 Kings Garden Way, Falls Church, VA 22043, 703-448-3394 (H), 703-903-9056 (F), hwolf@gmuvax.gmu.edu

DEFENSE R&D POLICY: Mr. Joe Gruessing, Westinghouse Electric, P. O. Box 746, M/S 1675, Baltimore, MD 21203, 410-765-7070 (W), 410-461-2234 (H) ENERGY POLICY: Mr. Jerry Fussell, JBF Associates, Inc., 1000 Technology Park Center, Knoxville, TN 37923.

1000 Technology Park Center, Knoxville, TN 37923, 615-966-5232 HEALTH CARE ENGR. POLICY: Mr. John Adams, Valley

Lab Inc., 5920 Longbow Drive, Boulder, CO 80301, 303-530-6503 (W), 303-443-8973 (H) COMR (Man and Radiation): Mr. Richard L. Doyle, Doyle

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(info.ieeeusa.pension@ieee.org). To obtain these docu-

address (no subject line or text message required). An

autoresponse text file will be automatically returned to

Conference Calendar

DATE & PLACE

CONFERENCE

CALLS FOR PAPERS 1995

26-30 June 1995 COMPASS '95 — 10th Annual Conference Gaithersburg, MD on COMPuter ASSurance

(See ad on page 11.)

6-7 July 1995 Tokyo, JAPAN

25th Reliability & Maintainability Symposium

Sponsored by the Union of Japan Scientists and Engineers (UJSE) in cooperation with the IEEE Tokyo Reliability Chapter. The symposium welcomes papers focusing on:

- Component . device and system reliability
- Mechanical and structural reliability
- Reliability and maintainability management
- Reliability design theory and techniques
- Data collection and analysis
- Reliability testing
- Failure analysis and reliability physics
- Maintainability and availability
- Reliability and safety
- SAoftware reliability and computer aided reliability engineering
- TQC, TQM, and reliability

Abstracts must be received by 10 January 1995.

Please mail to: Professor Michio HORIGOME, Chairperson, IEEE Reliability Tokyo Chapter, Tokyo University of Mercantile Marine, Department of Electronic and Mechanical Engineering, 2-1-6 Etchujima, Koto-Ku, Tokyo, 135 JAPAN, Tel & Fax: +81 3-245-7421

Hyatt Phoenix Hotel

11-14 Sept. 1995 17th Annual Electrical Overstress/Electrostatic Discharge Symposium

Phoenix, AZ USA

The 17th annual symposium dealing with electrical overstress (EOS) and electrostatic discharge (ESD) effects is being sponsored by the ESD Association in cooperation with IEEE. The symposium will be devoted to the fundamental understanding of electrical transients and electrical overstress, and the application of this knowledge to the solution of problems in military, industrial, computing and communication, consumer and automotive electical components as well as in systems, subsystems and equipment. Although historically the symposium has focused on preventing damage to sensitive components in the solid-state electronics industryu, quality contributions relating to EOS/ESD are actively solicited from other industries including manufacturing and biomedical.

Papers may deal with work in the following or related areas:

Failure Mechanisms

- Modeling and Physics of Damage
- Breakdown of Thin Dielectric Layers
- Shallow Junction and Contact Failure

- Damage of VLSI Chip Interconnections
- Latent Failures

Protection Circuits and Devices

- New Materials, Processes and Devices
- New Circuit and Layout Design
- Optimal Protection for HBM and CDM
- Latchup

System Effects

- Chip Protection During Wafer Processing
- Simulator and Event Characterization
- Transient ESD/EMI-Induced Upset
- New Circuit/Enclosure Design
- Troubleshooting Techniques

Factory and Control Issues

- Effectiveness of Air Ionization
- Facility, Packaging and Handling
- EOS/ESD Control Programs

Measurement and Testing

- Test Methods and Procedures
- Specifications and Standards
- Simulation and Prediction
- Failure Analysis Techniques

New Topics

- Biomedical Effects
- ESD Control in Explosives Industry
- Wafer Charging and Plasma Effects
- ESD-Induced Lock-Up of Automated Equipment
- High-Voltage and Automotive ESD
- Other New Topics

Authors must submit a 50-word abstract and a 300- to 500-word summary, and a maximum of one page of figures (optional) appropriate to describe a twenty minute paper. The 50-word abstract should be typed on a separate sheet and include the title of the talk, name(s), and affiliation(s) of the author(s), complete return address(es) and telephone number(s). The abstract is intended for publication in the advance program. The 300- to 500-word summary must be submitted in a double-spaced typewritten format suitable for review purposes by the committee. The summary must clearly state: 1) the purpose of the work, 2) the results of the work, 3) how it advances knowledge in EOS/ESD. Title and authors' name(s) should appear on each page. The deadline for submissions is January 18, 1995. Abstracts and summaries should be submitted by postal or electronic mail, not faxed.

Please forward abstracts and summaries to:

Technical Program Chairman: Robert G. Renniger, AT&T Bell Labs, Rm. 1A-201, 600 Mountain Avenue, Murray Hill, NJ 07974, Tel: (908) 582-4122, Email: r.g.renninger@att.com Europe: Horst Gieser, Fraunhofer Institute IFT-TMS, Hansastrasse 27D, D-80686 Munich, GERMANY, Tel: (49) 89 54759-020, Email: gieser@ift.fhg.de

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CONFERENCES 1994

Stanford Sierra Camp,

16 - 19 Oct. 1994 1994 INTERNATIONAL INTEGRATED RELIABILITY WORKSHOP (Formerly the Wafer Level Reliability

Lake Tahoe, CA Workshop)

USA

WORKSHOP EXPERIENCE

In response to the need for a broader and more cross-functional approach to semiconductor reliability engineering, the Workshop explores a broad range of topics that are critically relevant to the semiconductor business community and offers attendee participation in a variety of forms. The Workshop features presentations. tutorials, open poster sessions, moderated discussion group sessions, and special interest group (SIG) meetings.

MAJOR TECHNICAL THEMES

This year, we are continuing to emphasize the topic of building in reliability (BIR), for devices and packages, while we maintain our focus on key topics in wafer level reliability. We will also introduce a new topic: Reliability Modeling and Simulation (RM&S).

DISCUSSION GROUPS

The evening discussion topics/issues are: 1) WAFER LEVEL RELIABILITY, 2) BUILDING IN RELIABILITY, 3) QUALIFICATION ELIMINATION, 4) RELIABILITY MODELING & SIMULATION

OPEN POSTER SESSIONS

The Technical Program will include two open poster sessions.

We are again offering two tutorials on Sunday afternoon: 1) The Practical Side of Thin Dielectric Monitoring and Characterization – J. S. Suehle, C. Messick & B. Langley, 2) Mobile Ion Contamination in CMOS Circuits: A Clear and Present Danger - M. A. Chonko, K. Erington & R. L. Hance

SPECIAL INTEREST GROUPS

This year is the third anniversary of our Special Interest Group (SIG) effort. The SIG program at the Workshop has been very successful in fostering collaborative work on important reliability issues and we look forward to continuing growth and renewal in our SIGs. The SIG activities at the Workshop this year will focus on promoting the formation of SIGs as a natural extension of the Discussion Group sessions.

If you have any question on the technical program, please contact: Barbara Vasquez, by telephone (602)413-4696 / fax 4511, or by email RRHB40@email.sps.mot.com

For more registration information, please call (315)339-3971.

14-17 Nov. 1994 Tenth International Conference of the Jerusalem Crowne Israel Society for Quality Plaza Holiday Inn

Convention Center Jerusalem, ISRAEL

This year's theme will be "Quality: The Star that Leads to a Better World." A commercial exhibition will take place within the framework of the conference. The conference will be conducted in English and Hebrew. Some simultaneous translations will be offered. Hotel accommodations within walking distance have been reserved by I.G.T. Group Travel Ltd. Registration fees are US\$310 for 3 days (includes technical sessions, tutorials, book of proceedings, conference kit, welcome reception, lunch and coffee breaks), US\$225 for 2 days (sessions only), US\$150 for 1 day, and US\$170 for tutorials only. For more information contact: Conference Secretariat, c/o ISAS International Seminars, P.O. Box 574, Jerusalem, 91004, Israel, Fax: 972-2-666154, Phone: 972-2-661356.

1995

16-19 Jan. 1995 Annual Reliability and Maintainability Washington Hilton Symposium Hotel and Towers Theme: Reliability and Maintainability — Washington, D.C. The Next Generation USA

(See ad on page 12.)

March 8-10, 1995 Second Issat International Conference on Orlando, FL Reliability and Quality in Design USA

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- Quality Control and Reliability Engineering Division of IIE

THEME

The ISSAT International Conference on Reliability and Quality in Design is an international forum for presentation of new results, research development, and applications in reliability and quality in design. Papers address aspects of reliability and quality in design with case studies, experimental results, or applications of new or well-known theory to the solution of actual reliability and quality problems in engineering design.

TOPICS

- Reliability
- Modeling Analysis and Simulation
- Fault Tolerance
- Ouality Assurance ■ Optimization
- Software Reliability and Testing
- Quality Cost
- Maintainability and Availability
- Data Collection and Analysis
- Human Factors and Reliability
- Concurrent Engineering and Design
- Performance Analysis
- Experimental Design for Quality Control
- Software and Algorithms
- Methodologies for Quality Control
- Systems Design
- Safety-Critical Systems
- Risk Assessment Modeling
- Reliability Modeling and Testing
- Network Reliability
- Design Issues in Manufacturing
- Process Control and Management
- Quality Planning and Measurements

Reliability Society Newsletter October 1994

- Engineering Deign Optimization
- Quality Engineering
- Total Quality Management Techniques

For information contact: Program Chairman Dr. Hoang Pham, Dept. of Industrial Engineering, Rutgers University, P.O. Box 909, Piscataway, NJ 08855 U.S.A., Tel: (908) 445-5471. Fax: (908) 445-5467, e-mail: hopham@princess.rutgers.edu

13-16 March 1995 15th Capacitor and Resistor Technology Hyatt Islandia Symposium Hotel

San Diego, CA

The symposium is an annual forum for the presentation of information on new components, improved applications and solutions to current problems. The Conference is designed to exchange information between users, manufacturers and academia on the following components:

- Capacitors
- Magnetics
- Filters
- Resistors

This year there will be the usual technical and product sessiont with a special session on High Temperature Components and Applications. Technical sessions are planned on the following topics:

- Application Experience
- Screening Methods
- Problems and Solutions
- Quality Assessment
- Failure Experience
- Failure Analysis Procedures
- Reliability Performance
- Test Techniques
- Derating Practices
- High Reliability Practices
- Materials
- Performance Data
- Processes
- Future Trends and Projections
- Special: Hight Temperature Performance and Applications

For more information contact: CARTS, 904 Bob Wallace Ave., Suite 117, Huntsville, AL 35801 USA, Tel: (205)536-1304, Fax: (205)539-8477

3-6 April 1995 Riviera Hotel Las Vegas, NV

International Reliability Physics Symposium

The 1995 Symposium will continue emphasizing building-in reliability for VLSI devices and hybrid components during their design, manufacture and test. Papers illustrate the incorporation of reliability physics, reliability engineering, out-of-spec design tolerance, fabrication, assembly, and manufacturing process control to improve system reliability.

TOPICS:

10

■ BUILDING-IN RELIABILITY:

- Integration of reliability engineering with all elements of design
- Establishing effects of input parameters on product reliability & control
- Physical basis for design rules & concepts for minimizing jeopardy with experimental validation

- Particulate control and its effects on reliability
- Improved manufacturing techniques for wafer fabrication and assembly
- TESTING METHODOLOGIES FOR RELIABILITY. including:
- In-process wafer fabrication control and assembly, monitors, and sensors
- Novel test structures and materials
- Evaluation at wafer level or after full or partial processing
- Reliability modeling & field failure rate prediction
- ANALYZING FOR RELIABILITY:
- VLSI failure mechanisms and models applied to: dielectric integrity; electromigration; hot-carriers; low power/low voltage issues; corrosion; latchup/ESD/EOS
- Optoelectronic failure mechanisms and models applied to: LED/laser degradation; lithographic wave guide; burn-in/aging/wearout; passive element degradation; optical fiber issues: ESD/EOS
- Assembly related failure mechanisms and models applied to: bonding; surface mount issues; multichip packages; package integrity; thermomechanical stress; die overcoats
- System related failure mechanisms, including: automotive; consumer; military & aerospace
- Failure analysis techniques: new, advanced, & simplified
- Analytical instruments & techniques
- Computer-Aided Reliability (CAR) applications & simulation with experimental validation

For more information contact: Aiit K. Goel, Technical Program Chairman, 1995 IRPS, Oneida Research Services, Inc., 540 Weddell Drive, Suite 7, Sunnyvale, CA 94089 USA, Tel: 408-734-2987, Fax: 408-734-2984, e-mail: AjitG@AOL.com

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COMPASS '95 10th Annual Conference on COMPuter ASSurance

26-30 June 1995 Gaithersburg, MD

The purpose of COMPASS is to bring together researchers, developers, integrators, and evaluators who work on problems related to specifying, building, and certifying high-assurance, high-consequence computer systems. What distinguishes COMPASS from similar conferences is its emphasis on bridging the gap between research and practice. For researchers this provides an opportunity to present new results, theories, and techniques both to other researchers, and to practitioners who can put them to use. They can also learn from practitioners of issues and problems encountered in building real systems. Practitioners have an opportunity to share lessons learned, to hear of new research, and to influence future research directions.

COMPASS '95 will be held at the National Institute of Standards and Technology in Gaithersburg, MD, a suburb of Washington, DC.

Papers should present advances in the theory, design, implementation, evaluation, or application of high-assurance systems, or report on experiments, evaluations, and open problems in the use of new technologies for computer assurance. Special consideration will be given to presentations (either single papers or paper pairs) by practitioners and researchers who have teamed-up to work on the same problem. The conference will be preceded by one or two days of tutorials. There will also be a tools fair.

Relevant Subjects for papers, and also for proposals for panel session, tutorials, and the tools fair are solicited include the following:

Software Safety Software Reliability **Human-Computer Interfaces** Tools Real-Time Systems Networks **Embedded Systems** Certification Measurements and Metrics Standards

Representative Application Areas of Interest include but are not limited to:

Road and Rail Transport Systems Communciations Plant and Process Control Systems **Avionics**

Nuclear and Conventional Power Generation

Military Systems Medical Systems Space Systems

Computer Security

Organization Theory

Life Cycle Processes

11

Formal Methods

V&V Practices

Instructions to Authors:

Send five copies of your paper (not to exceed 7500 words), panel session proposals, tutorial proposals, or tools fair proposals to John Rushby, Program Chair, at the address given below. Abstracts, electronic submissions, late submissions, overlength papers, papers previously published or currently submitted for publication elsewhere, and papers that cannot be published in the proceedings will not be considered. Papers submitted from outside North America should be sent via overnight courier service or express mail. Exceptionally, authors in countries where copying or printing facilities are limited may submit a single copy in any form available to them (including electronic mail). Authors are responsible for obtaining, prior to acceptance, any and all necessary permissions and clearances for publication, and are expected to present their paper in person if it is accepted. Limited financial assistance will be available for student authors.

PAPER SUBMISSION DEADLINE: January 17, 1995 NOTIFICATION OF ACCEPTANCE: March 14, 1995 CAMERA-READY COPIES DUE: April 17, 1995

The proceedings will be published by the IEEE. Papers that describe use of technology presented at a previous COMPASS conference are eligible for a special award. Papers of exceptional quality and appropriate subject matter are eligible for inclusion in a special issue of the Journal of High Integrity Systems or the Journal of Computer Security.

FOR ADDTIONAL INFORMATION CONCERNING COMPASS '95 CONTACT:

Bonnie Danner, General Chair COMPASS '95 TRW Systems Division ONE Federal Systems Park Drive Fairfax, VA 22032-4417 USA

Tel: (703) 876-4383 Fax:(703)876-4304 Email: bonnie.danner@trw.sprint.com John Rushby, Program Chair Computer Science Laboratory SRI International

333 Ravenswood Avenue Menlo Park, CA 94025 USA

Tel: (415) 859-5456 Fax: (415)859-2844 Email: rushbv@csl.sri.com

October 1994

1995 ANNUAL INTERNATIONAL RELIABILITY AND MAINTAINABILITY SYMPOSIUM AND EXHIBITS PROGRAM

The International Symposium on Product Quality & Integrity Sponsored by IEEE/RS in cooperation with 9 other Technical Societies

16-19 January 1995

Washington Hilton Hotel & Towers

Washington, D.C. USA

Reliability and Maintainability — The Next Generation

Tutorial Sessions

Monday, January 16 is devoted entirely to Tutorial Sessions. Additional Tutorials will also be held parallel to the Technical and Panel sessions throughout the Symposium. The Tutorial faculty is comprised of expert practitioners in their fields. Tutorial topics will fill needs from basic theory to advanced material, and will include: Reliability; Maintainability; Practical R&M Management; Taguchi Experiments; Markov Modeling; Understanding Part Failure Mechanisms; Software Reliability; Fault Tolerant Computing; Concurrent Engineering; and others.



Panel Sessions

In addition to the Technical Sessions, the Symposium will include a number of Panel Sessions, ranging from the Advisory Board to Invited Sessions, covering current controversial topics. At press time, the Panel Sessions planned include: Influence of Systems Engineering & Operations Methods on Product Quality; Virtual Reality Applications; Design & Verification of Safe, Reliable, and Robust Airplane Systems; Automotive Applications; Use and Misuse of Reliability Predictions

Technical Paper Sessions

Tuesday through Thursday, January 17 - 19, will include a topical range of Technical Sessions comprised of the best papers submitted in response to the Call For Papers. These sessions will include:

Space Programs Reliability
Fuzzy Logic
R&M Testing
Fault Trees
BIT/BITE

Practical Aerospace Applications of Reliability
Concurrent Engineering Enabling Technologies
Automated Modeling and Simulation Tools
Safety & Quality Management Systems
CALS Applications to R&M

R&M Requirements System Modeling R&M Growth Machine Tool R&M RAM/CAE Tools

Leesburg Conference

Once again, the IEEE, Leesburg CAE Workshop on Concurrent Engineering for Integrated Product Development (IPD) is teaming up with RAMS. The workshop will be held on Monday, and is a must if IPD Teams are part of your work.

Exhibits Program

For the 11th year in a row, the Symposium will include Exhibits in key technical areas such as Supportability, CAD/CAM/CAE/CAT, Failure Analysis, R&M Software, ESS and Logistics. Efforts are underway to expand the coverage to new technology areas to parallel some of the new sessions this year, such as Virtual Reality Applications.

The single, low registration fee includes admission to all five of these programs, a full set of Tutorial Notes, and a bound copy of the Symposium Proceedings, with the full text of all technical papers. (Together nearly 1000 pages of top-level technical material). With proper planning by you or your company, this exceptional value can be utilized as training for new or experienced professionals, as well as the opportunity to keep abreast of the latest technical developments. PLAN TO ATTEND THIS SYMPOSIUM!!! The fee is appreciably less than half the usual cost of four day tutorials presented by any other forum. This is possible because of the not-for-profit structure of the RAMS, major industry support, and the volunteer contribution of the Management Committee and Board of Directors.

For more information contact:
Alfred M. Stevens
Lockheed Space Op. Co.
200 Cordoba Court
Merritt Island, FL 32953 USA
(407) 861-0745 FAX (407) 861-5922

For exhibit information contact:

Dave Barber
Scien-Tech Associates, Inc.
P.O. Box 3048
Sarasota, FL 34230-3048 USA
(813) 355-5207 FAX (813) 953-3175

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